

Docket No. 245557US05X



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

IN RE APPLICATION OF: Masanobu OGINO, et al.

SERIAL NUMBER: 10/713,054

ATTN: APPLICATION BRANCH

FILING DATE: November 17, 2003

FOR: SEMICONDUCTOR SUBSTRATE AND METHOD OF MANUFACTURE THEREOF

**FILING OF DECLARATION UNDER 37 CFR 1.53(f)**

COMMISSIONER FOR PATENTS  
ALEXANDRIA, VIRGINIA 22313

SIR:

Responsive to the notification dated February 25, 2004, and in accordance with the provisions of 37 CFR 1.53(f), Applicants submit herewith a Rule 63 Declaration. The required fee was paid at the time of filing the application.

The Declaration enclosed herewith, attached to the specification, is believed to adequately identify the above-identified application in accordance with 37 CFR 1.63, as set forth in MPEP Section 601.01.

The undersigned hereby states that the specification to which the Declaration is attached is a true copy of the specification, and any amendments thereto, as originally filed in the Patent Office in order to obtain a filing date.

In light of the foregoing, this application is deemed to be in proper condition for examination and such favorable action is earnestly solicited.

Respectfully Submitted,

OBLON, SPIVAK, McCLELLAND,  
MAIER & NEUSTADT, P.C.

A handwritten signature in dark ink, appearing to read "Norman F. Oblon", written over a horizontal line.

Norman F. Oblon

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## DECLARATION FOR PATENT APPLICATION

03S1260-1

As a below named inventor, I declare:  
that I verily believe myself to be the original, first and sole (if only one individual inventor is listed below) or an original, first and joint inventor (if more than one individual inventor is listed below) of the invention in

## SEMICONDUCTOR SUBSTRATE AND METHOD OF MANUFACTURE THEREOF

the specification of which is attached hereto unless the following box is checked.

☐ was filed on \_\_\_\_\_ as United States Application  
or PCT International Application No. \_\_\_\_\_, and  
was amended on \_\_\_\_\_ (if applicable).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information of which is material to patentability as defined in 37 CFR 1.56.

I hereby claim foreign priority benefits under 35 U.S.C. 119(a)-(d) or 365 (b) of any foreign application(s) for patent or inventor's certificate, or 35 U.S.C. 365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below any foreign application for patent or inventor's certificate, or PCT International application having a filing date before that of the application on which priority is claimed:

<u>Country</u>	<u>Category</u>	<u>Application No.</u>	<u>Filing Date</u>	<u>Priority Claim</u>
Japan	Patent	2002-333682	November 18, 2002	Yes
Japan	Patent	2003-101614	April 4, 2003	Yes

I hereby appoint the registrants of Oblon, Spivak, McClelland, Maier & Neustadt, P.C., 1940 Duke Street, Alexandria, Virginia 22314, Customer No. 22850, or any one of them. Send correspondence to Oblon, Spivak, McClelland, Maier & Neustadt, P.C., 1940 Duke Street, Alexandria, Virginia 22314, Telephone No. (703)413-3000.

I declare further that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

# DECLARATION FOR PATENT APPLICATION

03S1260-1

I declare further that my citizenship, residence and mailing address are as stated below next to my name:

<u>Inventor: (Signature)</u>	<u>Date</u>	<u>Residence and mailing address</u>
<u>Masanobu Ogino</u> Masanobu Ogino	<u>Date: Nov. 25, 2003</u> <u>Citizen of: Japan</u>	<u>6-6-503, Green-Heights,</u> <u>Yokosuka, Kanagawa, Japan</u>
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<u>Yoshiro Baba</u> Yoshiro Baba	<u>Date: Nov. 25, 2003</u> <u>Citizen of: Japan</u>	<u>3-17-6, Nakahara, Isogo-ku,</u> <u>Yokohama, Kanagawa, Japan</u>
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